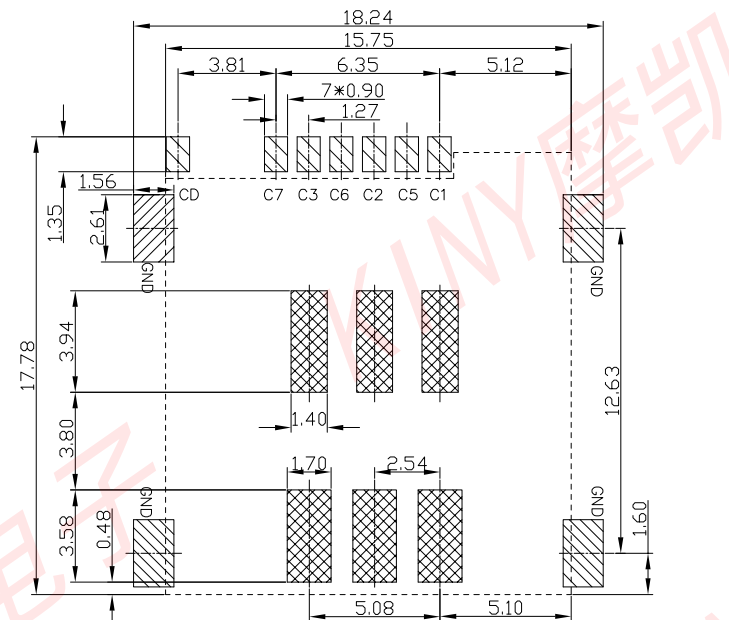
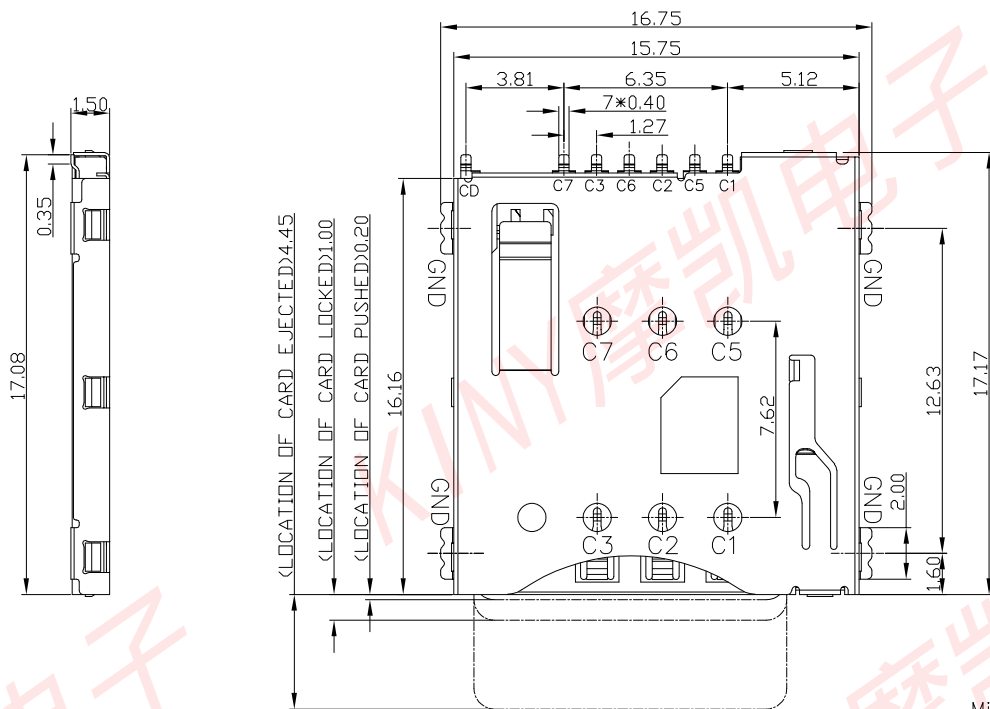


* 所有原料材质, 生产制程, 电镀必须符合HSE要求



RECOMMENDED P.C.B LAYOUT
COMPONENT SIDE(TOLERANCE ±0.05)

▨ PAD AREA
▩ KEEP OUT AREA

TECHNICAL CHARACTERISTICS

1.General Characteristics

Dimensions: 15.75LX17.17WX1.50H mm

Weight: Approx 0.4±0.1g

Durability: 1500 cycles min.

2.Electrical Characteristics

Contact resistance;

Date Contact: 150mΩ max

CD Switch: 500mΩ max

Insulation resistance: >1000MΩ/500V DC

3.Solderability

Vapor phase: 215°C, 30sec.Max

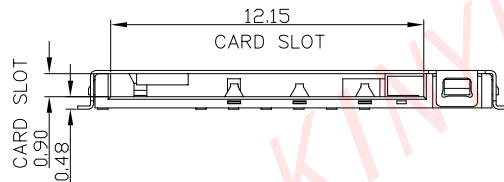
IR reflow: 250°C, 5sec.Max

Manual soldering: 370°C, 3sec.Max

4.Environmental Characteristics

Operating temperature: -40°C~+85°C

Operating humidity: 10%~+95%RH

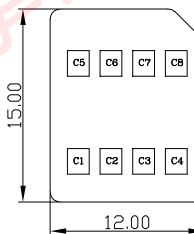


MicroSIM CARD	
Pin No.	NAME
C1	VCC
C2	RST
C3	CLK
C4	Reserved
C5	GND
C6	VPP
C7	I/O
C8	Reserved

ELECTRIC FUNCTION	DETECT SWITCH
WITHOUT CARD	CLOSED
CARD INSERTED	OPEN



MicroSIM CARD



SCALE 1:2

ITEM	PART NAME	Q'TY	MATERIAL	FINISH
1	HOUSING	1	Hi-temp Thermoplastic	Black UL94V-0
2	DATA CONTACT	6	Copper Alloy	Contact area:Gold plated
3	CD SWITCH	1	Copper Alloy	Contact area:Gold plated
4	SHELL	1	Stainless Steel	SMT area:Gold plated
5	COIL SPRING	1	SWP	
6	HEART CAM	1	Hi-temp Thermoplastic	Black UL94V-0
7	CAM PIN	1	Stainless Steel	

KINNY

东莞市摩凯电子有限公司

DIMENSIONS INIT: mm	
UNLESS OTHERWISE SPECIFIABLE	
DIMENSION	TOLERANCE
X.X: ±	0.35
X.XX: ±	0.25
X.XXX: ±	0.10
ANGULAR: ±	2'

PRODUCT NAME : Micro SIM P-P H1.50	DRAWING: Alexander	DATE: 2021.08.21
PRODUCT NO. : MS150-T1131-01-W	CHECK: Jack	DATE: 2021.08.21
DRAWING NO. : D-MC127-T1131-01-W	APPROVED: Jack	DATE: 2021.08.21
SCALE: 1:1	DWG ID: C D	REV.: A
PAGE: 1 of 1		

A	-----	NEW RELEASE	Alexander	2021.08.21
REVISION NO.	ECR NO.	DESCRIPTION	MARK	DATE
1				